FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16471

Generic Copy

04-Jun-2010

TITLE: Qualification of NCP370MUAITXG for Fabrication at TSMC Wafer Fab

PROPOSED FIRST SHIP DATE: 04-Sep-2010 or earlier with customer approval

AFFECTED CHANGE CATEGORY(S): ON Semi Fab Site / Subcontractor Fab Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Shilpa Rao < shilpa.rao@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Edmond Gallard
< edmond.gallard@onsemi.com >

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce that the NCP370MUAITXG is now qualified for production at the TSMC wafer fab in Taiwan.

Upon expiration or approval of the Final PCN, devices may be supplied from the TSMC wafer fab.

The TSMC wafer fab is compliant to ISO9001:2000, ISO/TS16949:2004, and ISO14001:2004. The NCP370MUAITXG has previously been manufactured at ON Semiconductor's Piestany, Slovakia wafer fab on the 0.8um PS5LV process. It is now qualified to run at TSMC on the 0.25um BCD process. Device performance will be the same among the qualified factories. No changes to packaging occur as a result of this wafer fab qualification. The NCP370MUAITXG will continue to be assembled and tested in existing, qualified locations.

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16471

RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Results
High Temp Op-Life	Tj = +150C, 168 hours	PASS (0/40)

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no significant difference in electrical parametric performance for the TSMC-sourced material. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

NCP370MUAITXG devices with date codes representing WW 31, 2010 or later will be assembled with die sourced from the TSMC wafer fab, unless earlier customer approval is obtained. If early customer approval is obtained, devices with date codes of WW 23, 2010 or later will be assembled with die from the TSMC wafer fab.

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16471

List of affected General Parts:

NCP370MUAITXG